LPARAY LOW-PROFILE OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH

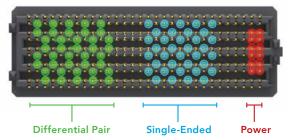


- Solder crimp termination for ease of processing
- Board stacking standoffs available to assist unmating and reduce risk for component damage on board



LPAM Series; 120 pins (actual size shown)

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS

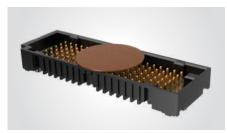
PITCH	TOTAL PINS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
1.27 mm x 1.27 mm	Up to 400 I/Os	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	2.2 A per pin (8 adjacent pins powered)	250 VAC	YES

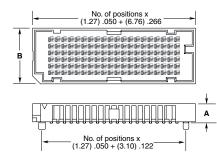


(1.27 mm) .050" PITCH • LOW-PROFILE OPEN-PIN-FIELD ARRAYS



LPAM
Board Mates:
LPAF
Standoffs:
JSO, SO



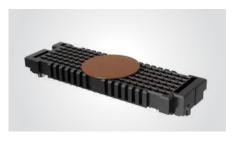


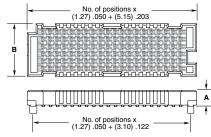
NO. OF ROWS	В	
-04	(8.18) .322	
-06	(10.72) .422	
-08	(13.26) .522	

LEAD STYLE	A	
-01.0	(3.68) .145	
-01.5	(4.19) .165	

View complete specifications at: samtec.com?LPAM

LPAF
Board Mates:
LPAM
Standoffs:
JSO, SO





NO. OF ROWS	В	
-04	(6.71) .264	
-06	(9.25) .364	
-08	(11.79) .464	

LEAD STYLE	A	
-03.0	(2.79) .110	
-03.5	(3.30) .130	

MATED HEIGHTS*				
	LPAF LEAD STYLE			
LPAM LEAD STYLE	-03.0	-03.5		
-01.0	(4.00) .157	(4.50) .177		
-01.5	(4.50) .177	(5.00) .197		

^{*}Processing conditions will affect mated height.

Notes:

Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?LPAF